

High and Low Side Driver

Features

- Floating channel designed for bootstrap operation
- Fully operational to +600 V
- Tolerant to negative transient voltage
- dV/dt immune
- Gate drive supply range from 10 V to 20 V
- Undervoltage lockout for both channels
- 3.3 V and 5 V logic compatible
- Matched propagation delay for both channels
- Logic and power ground +/- 5 V offset
- Lower di/dt gate driver for better noise immunity
- Output source/sink current 4 A / 4 A
- RoHS compliant

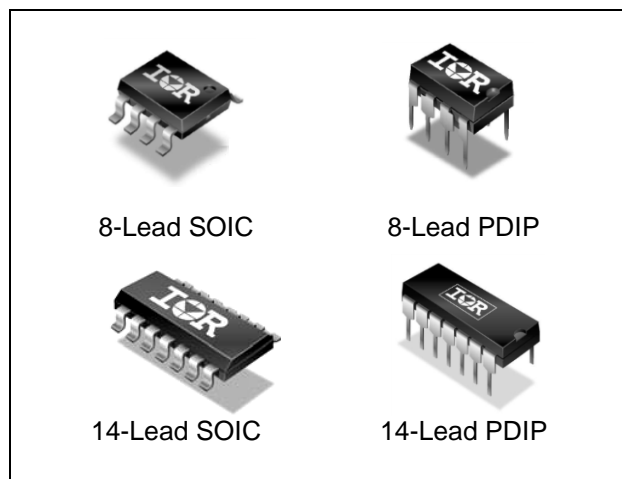
Description

The IRS2186(4) are high voltage, high speed power MOSFET and IGBT drivers with independent high-side and low-side referenced output channels. Proprietary HVIC and latch immune CMOS technologies enable ruggedized monolithic construction. The logic input is compatible with standard CMOS or LSTTL output, down to 3.3 V logic. The output drivers feature a high pulse current buffer stage designed for minimum driver cross-conduction. The floating channel can be used to drive an N-channel power MOSFET or IGBT in the high-side configuration which operates up to 600 V.

Product Summary

| | |
|---------------------|--------------|
| V_{OFFSET} | 600 V |
| $I_{\text{O+/-}}$ | 4 A / 4 A |
| V_{OUT} | 10 V – 20 V |
| Ton/off (typ.) | 170 & 170 ns |

Package Options

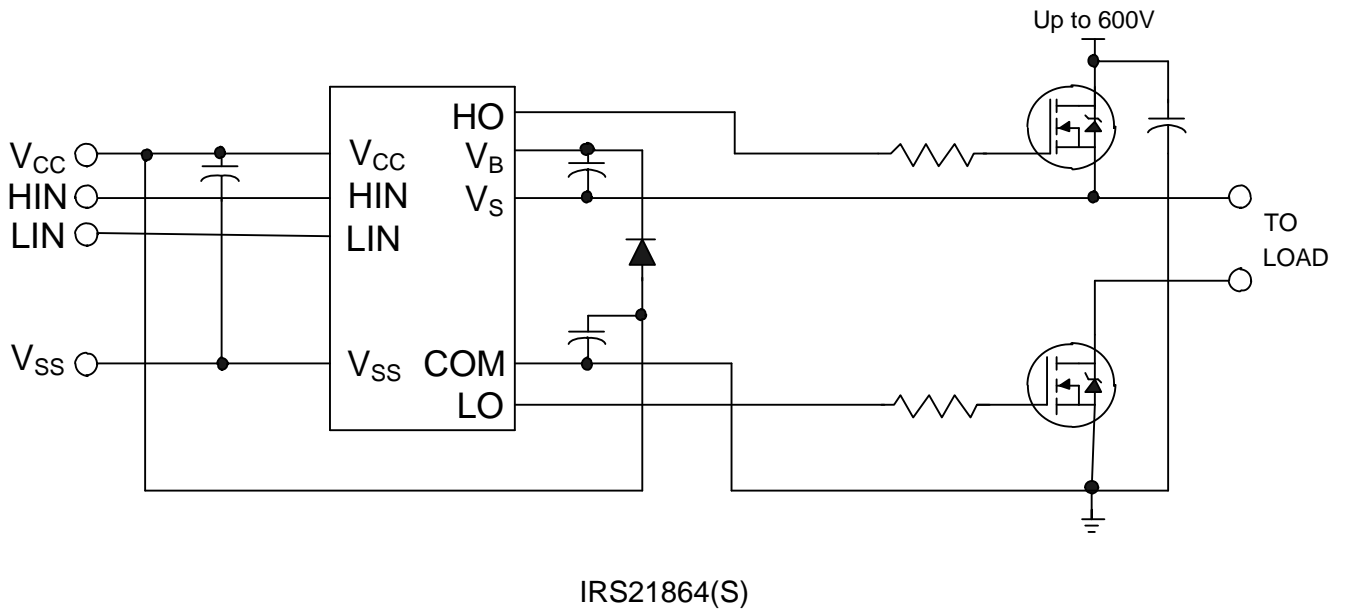
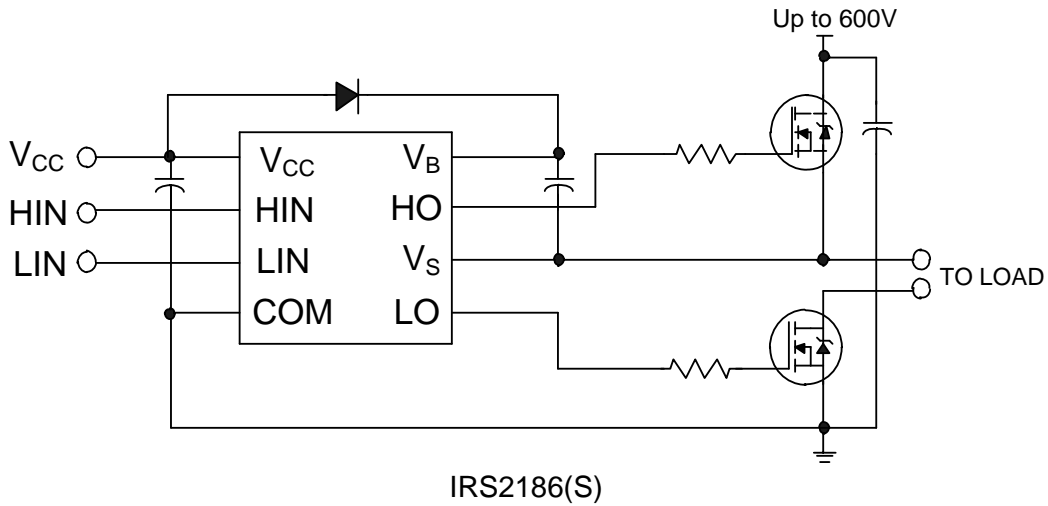


Ordering Information

| Base Part Number | Package Type | Standard Pack | | Orderable Part Number |
|------------------|--------------|---------------|----------|-----------------------|
| | | Form | Quantity | |
| IRS2186SPBF | SO8N | Tube | 95 | IRS2186SPBF |
| IRS2186SPBF | SO8N | Tape and Reel | 2500 | IRS2186STRPBF |
| IRS21864SPBF | SO14N | Tube | 55 | IRS21864SPBF |
| IRS21864SPBF | SO14N | Tape and Reel | 2500 | IRS21864STRPBF |
| IRS2186PBF | PDIP8 | Tube | 50 | IRS2186PBF |
| IRS21864PBF | PDIP14 | Tube | 25 | IRS21864PBF |

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Typical Connection Diagram



(Refer to Lead Assignments for correct pin configuration). These diagrams show electrical connections only. Please refer to our Application Notes and Design Tips for proper circuit board layout.

Absolute Maximum Ratings

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

| Symbol | Definition | Min. | Max. | Units | |
|------------|---|----------------|------------------|-------|------|
| V_B | High side floating absolute voltage | -0.3 | 620 [†] | V | |
| V_S | High side floating supply offset voltage | $V_B - 20$ | $V_B + 0.3$ | | |
| V_{HO} | High side floating output voltage | $V_S - 0.3$ | $V_B + 0.3$ | | |
| V_{CC} | Low side and logic fixed supply voltage | -0.3 | 20 [†] | | |
| V_{LO} | Low side output voltage | -0.3 | $V_{CC} + 0.3$ | | |
| V_{IN} | Logic input voltage (HIN & LIN) | $V_{SS} - 0.3$ | $V_{CC} + 0.3$ | | |
| V_{SS} | Logic ground (IRS21864) | $V_{CC} - 20$ | $V_{CC} + 0.3$ | | |
| dV_S/dt | Allowable offset supply voltage transient | — | 50 | V/ns | |
| P_D | Package power dissipation @ $T_A \leq +25^\circ\text{C}$ | 8 lead PDIP | — | 1 | W |
| | | 8 lead SOIC | — | 0.625 | |
| | | 14 lead PDIP | — | 1.6 | |
| | | 14 lead SOIC | — | 1 | |
| R_{thJA} | Thermal resistance, junction to ambient | 8 lead PDIP | — | 125 | °C/W |
| | | 8 lead SOIC | — | 200 | |
| | | 14 lead PDIP | — | 75 | |
| | | 14 lead SOIC | — | 120 | |
| T_J | Junction temperature | — | 150 | °C | |
| T_S | Storage temperature | -50 | 150 | | |
| T_L | Lead temperature (soldering, 10 seconds) | — | 300 | | |

Recommended Operating Conditions

The input/output logic timing diagram is shown in figure 1. For proper operation the device should be used within the recommended conditions. The V_S and V_{SS} offset rating is tested with all supplies biased at 15 V differential.

| Symbol | Definition | Min. | Max. | Units |
|----------|--|------------|------------|-------|
| V_B | High side floating absolute voltage | $V_S + 10$ | $V_S + 20$ | V |
| V_S | High side floating supply offset voltage | †† | 600 | |
| V_{HO} | High side floating output voltage | V_S | V_B | |
| V_{CC} | Low side and logic fixed supply voltage | 10 | 20 | |
| V_{LO} | Low side output voltage | 0 | V_{CC} | |
| V_{IN} | Logic input voltage (HIN & LIN) | V_{SS} | V_{CC} | |
| V_{SS} | Logic ground (IRS21864) | -5 | 5 | |
| T_A | Ambient temperature | -40 | 125 | °C |

† All supplies are fully tested at 25 V and an internal 20 V clamp exists for each supply

†† Logic operational for V_S of -5 V to 600 V. Logic state held for V_S of -5 V to $-V_{BS}$ (Please refer to the Design Tip DT97-3 for more details)

Dynamic Electrical Characteristics

V_{BIAS} (V_{CC} , V_{BS}) = 15 V, V_{SS} = COM, C_L = 1000 pF and T_A = 25 °C unless otherwise specified.

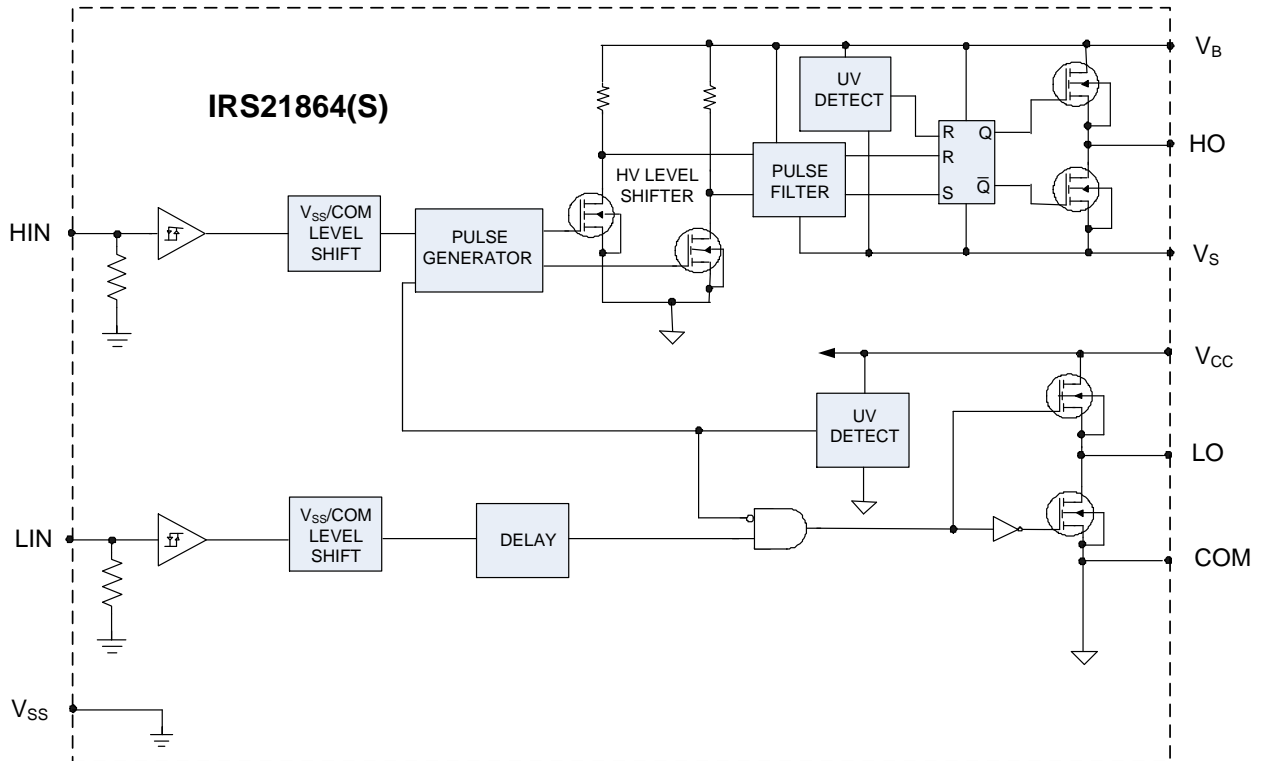
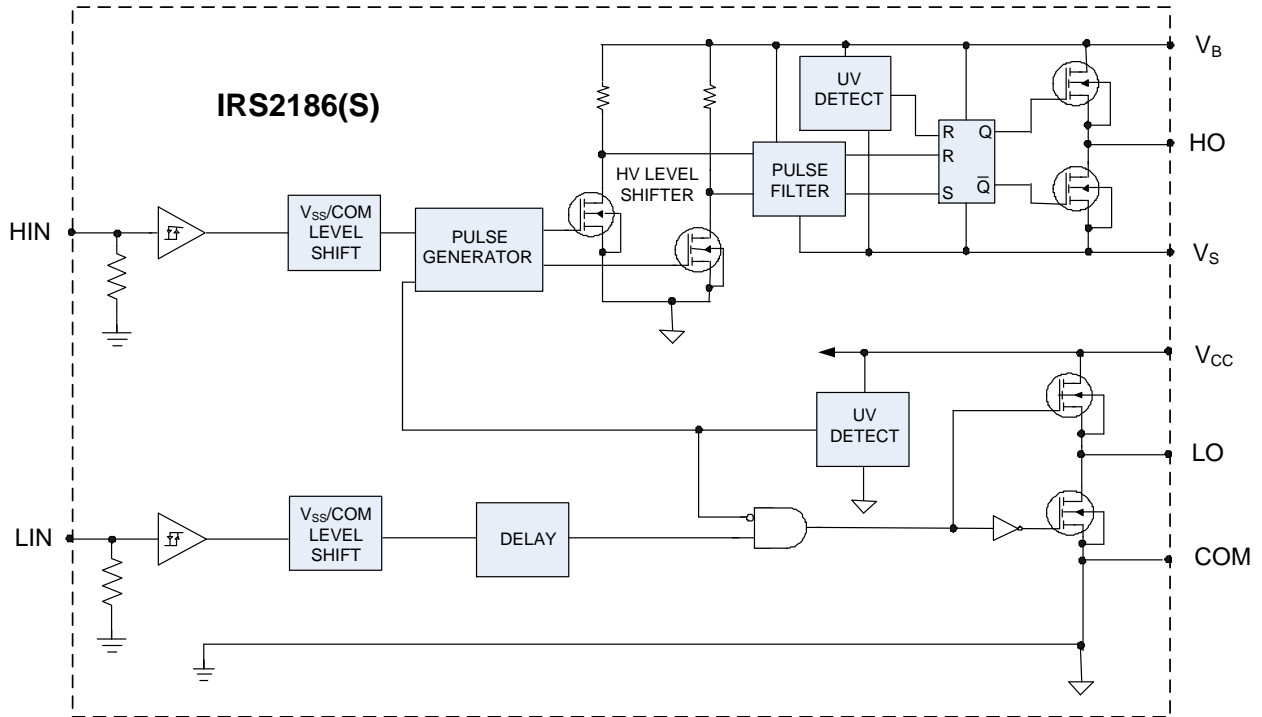
| Symbol | Definition | Min. | Typ. | Max. | Units | Test Conditions |
|-----------|-------------------------------------|------|------|------|-------|----------------------|
| t_{on} | Turn-on propagation delay | — | 170 | 250 | ns | $V_S = 0$ V |
| t_{off} | Turn-off propagation delay | — | 170 | 250 | | $V_S = 0$ V or 600 V |
| t_r | Turn-on rise time | — | 22 | 38 | | $V_S = 0$ V |
| t_f | Turn-off fall time | — | 18 | 30 | | |
| MT | Delay matching, HS & LS turn on/off | — | 0 | 35 | | |

Static Electrical Characteristics

V_{BIAS} (V_{CC} , V_{BS}) = 15 V, V_{SS} = COM, and T_A = 25 °C unless otherwise specified. The V_{IL} , V_{IH} , and I_{IN} parameters are referenced to V_{SS}/COM and are applicable to the respective input leads HIN and LIN. The V_O , I_O , and R_{ON} parameters are referenced to COM and are applicable to the respective output leads: HO and LO.

| Symbol | Definition | Min. | Typ. | Max. | Units | Test Conditions | |
|----------------------------|--|------|------|------|---------|---------------------------------------|----------------|
| V_{IH} | Logic "1" input voltage | 2.5 | — | — | V | $V_{CC} = 10$ V to 20 V | |
| V_{IL} | Logic "0" input voltage | — | — | 0.8 | | | |
| V_{OH} | High level output voltage, $V_{BIAS} - V_O$ | — | — | 1.4 | | | $I_O = 0$ A |
| V_{OL} | Low level output voltage, V_O | — | — | 0.15 | | | $I_O = 20$ mA |
| I_{LK} | Offset supply leakage current | — | — | 50 | μ A | $V_B = V_S = 600$ V | |
| I_{QBS} | Quiescent V_{BS} supply current | 20 | 60 | 150 | | $V_{IN} = 0$ V or 5 V | |
| I_{QCC} | Quiescent V_{CC} supply current | 50 | 120 | 240 | | | |
| I_{IN+} | Logic "1" input bias current | — | 25 | 60 | | | $V_{IN} = 5$ V |
| I_{IN-} | Logic "0" input bias current | — | — | 5 | | $V_{IN} = 0$ V | |
| V_{CCUV+} V_{BSUV+} | V_{CC} and V_{BS} supply undervoltage positive going threshold | 8 | 8.9 | 9.8 | V | | |
| V_{CCUV-} V_{BSUV-} | V_{CC} and V_{BS} supply undervoltage negative going threshold | 7.4 | 8.2 | 9 | | | |
| V_{CCUVH} V_{BSUVH} | Hysteresis | 0.3 | 0.7 | — | | | |
| I_{O+} | Output high short circuit pulsed current | 2 | 4 | — | A | $V_O = 0$ V, $PW \leq 10$ μ s | |
| I_{O-} | Output low short circuit pulsed current | 2 | 4 | — | | $V_O = 15$ V, $PW \leq 10$ μ s | |

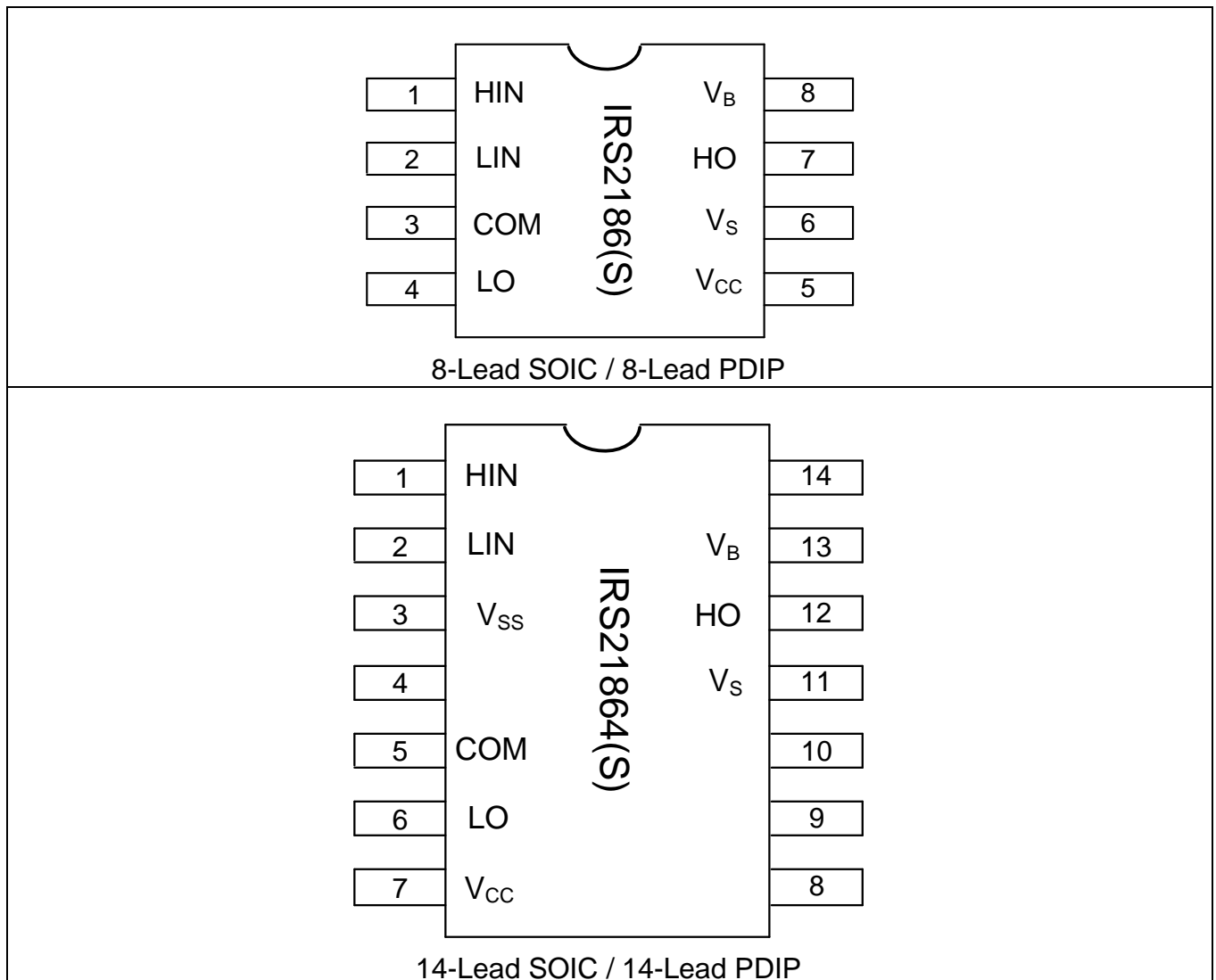
Functional Block Diagram



Lead Definitions

| Symbol | Description |
|-----------------|---|
| HIN | Logic input for high side gate driver output (HO), in phase |
| LIN | Logic input for low side gate driver output (LO), in phase |
| V _{SS} | Logic ground (IRS21864) |
| V _B | High side floating supply |
| HO | High side gate drive output |
| V _S | High side floating supply return |
| V _{CC} | Low side and logic fixed supply |
| LO | Low side gate drive output |
| COM | Low side return |

Lead Assignments



Application Information and Additional Details

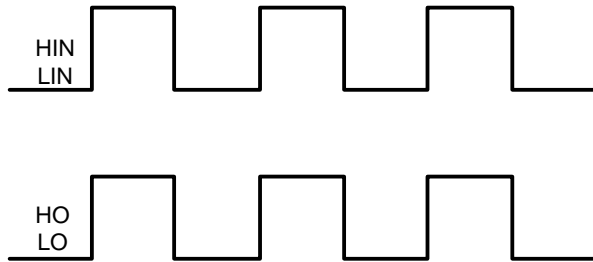


Figure 1. Input/Output Timing Diagram

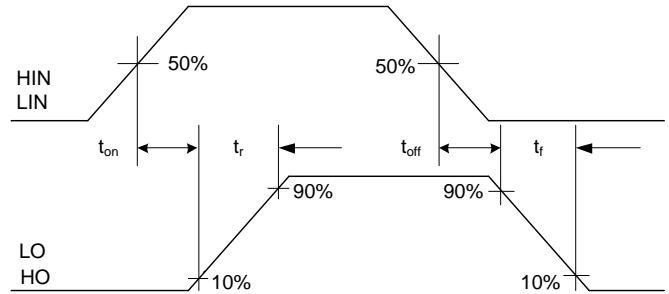


Figure 2. Switching Time Waveform Definitions

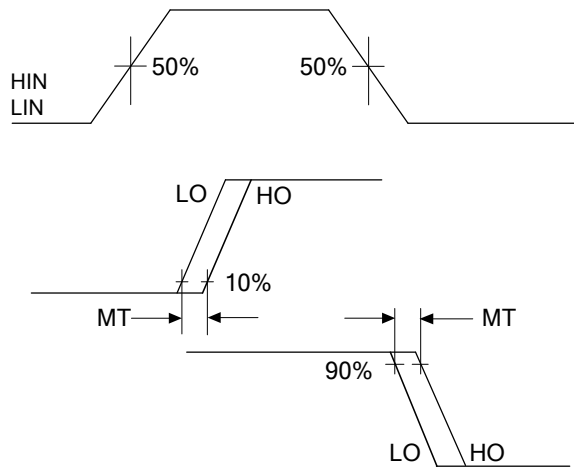


Figure 3. Delay Matching Waveform Definitions

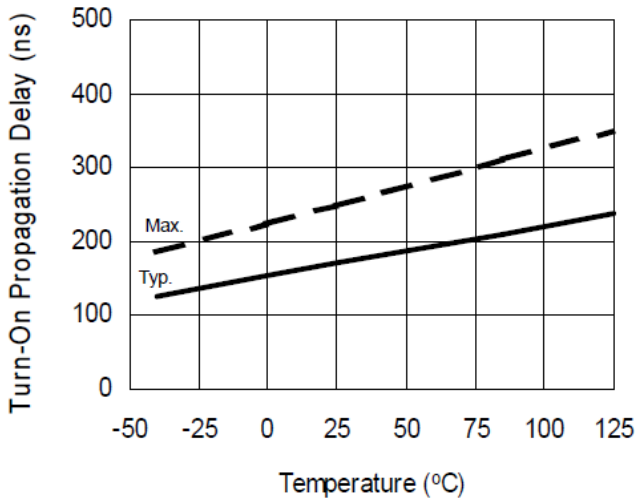


Figure 4A. Turn-On Propagation Delay vs. Temperature

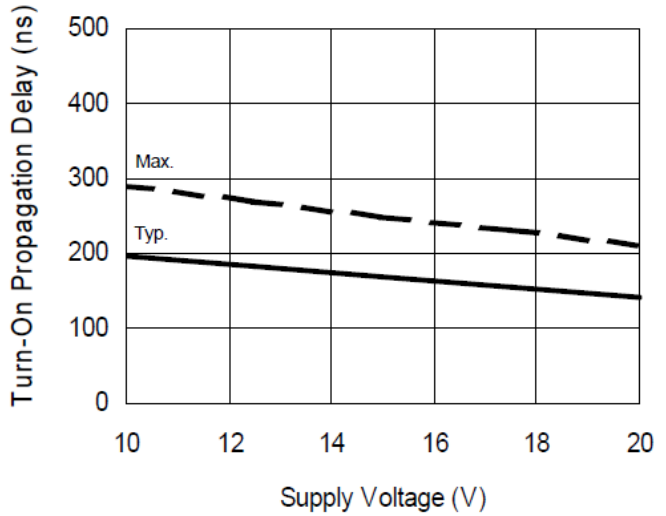


Figure 4B. Turn-on Propagation Delay vs. Supply Voltage

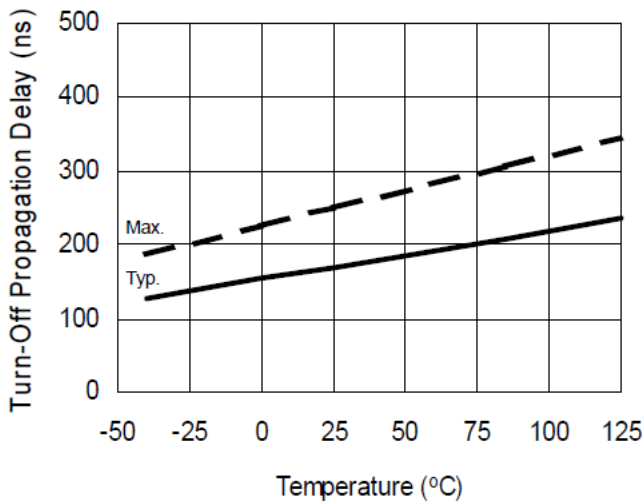


Figure 5A. Turn-Off Propagation Delay vs. Temperature

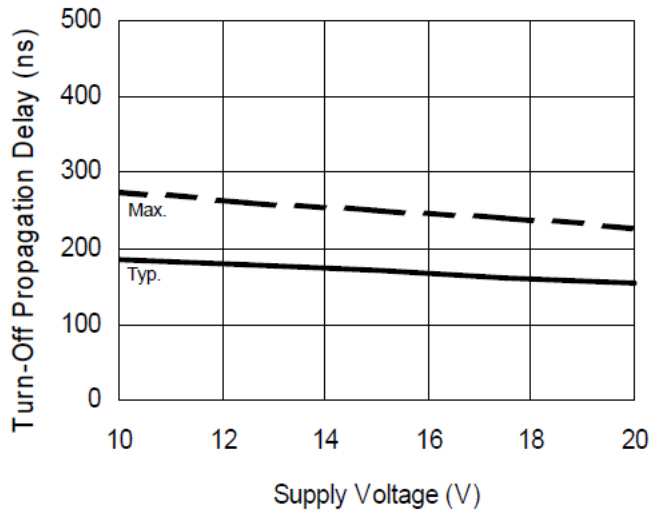
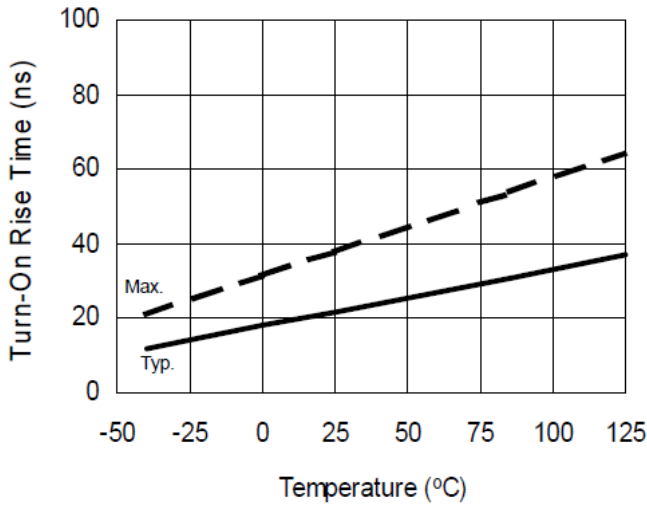


Figure 5B. Turn-Off Propagation Delay vs. Supply Voltage



6A. Turn-On Rise Time vs. Temperature

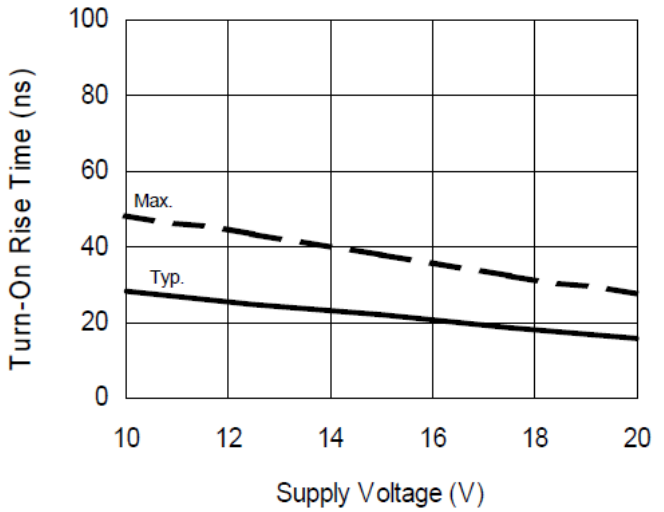


Figure 6B. Turn-On Rise Time vs. Supply Voltage

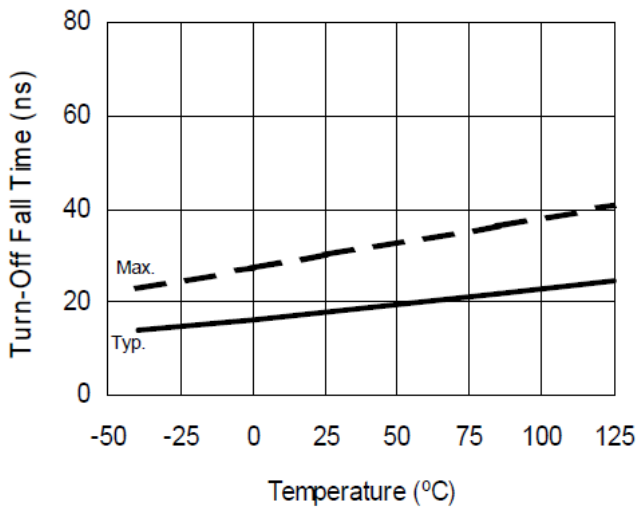


Figure 7A. Turn-Off Fall Time vs. Temperature

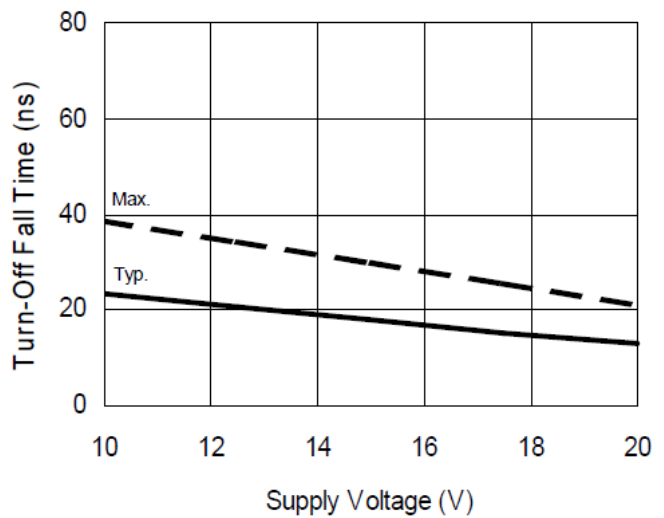


Figure 7B. Turn-Off Fall Time vs. Supply Voltage

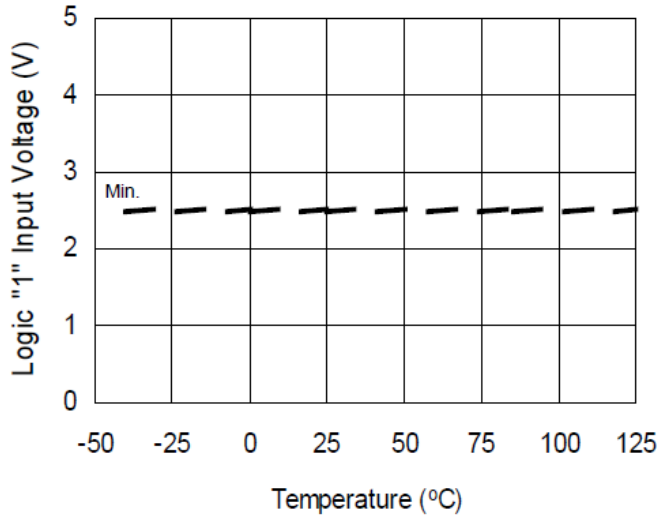


Figure 8A. Logic "1" Input Voltage vs. Temperature

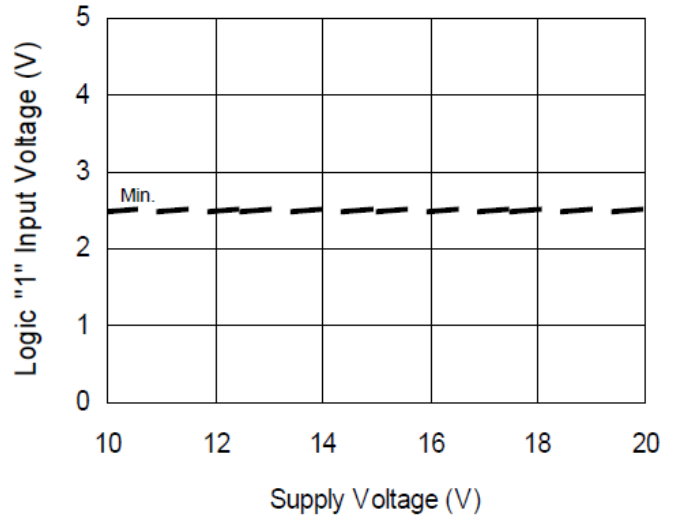


Figure 8B. Logic "1" Input Voltage vs. Supply Voltage

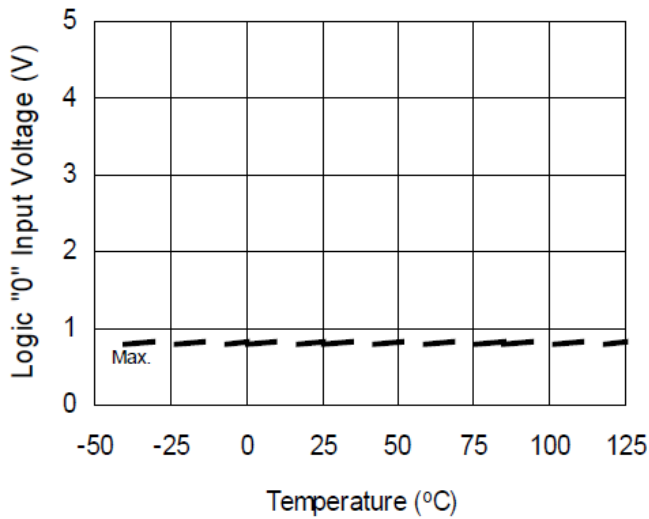


Figure 9A. Logic "0" Input Voltage vs. Temperature

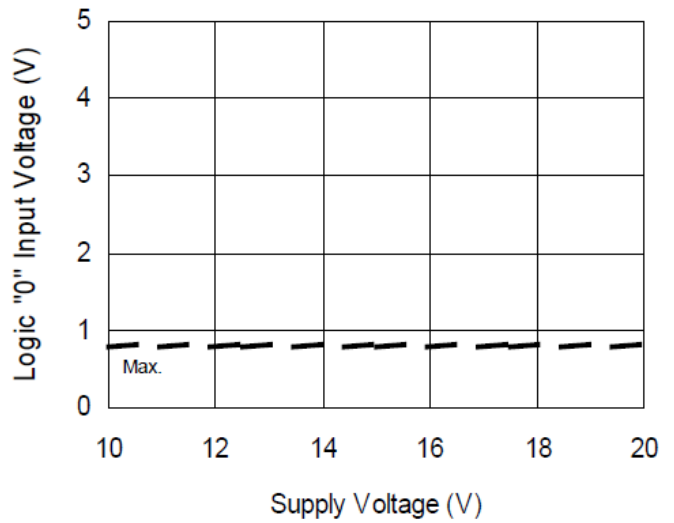


Figure 9B. Logic "0" Input Voltage vs. Supply Voltage

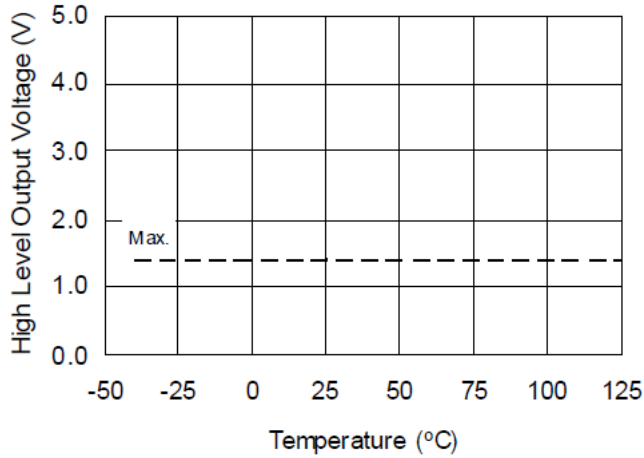


Figure 10A. High Level Output Voltage vs. Temperature (Io = 0mA)

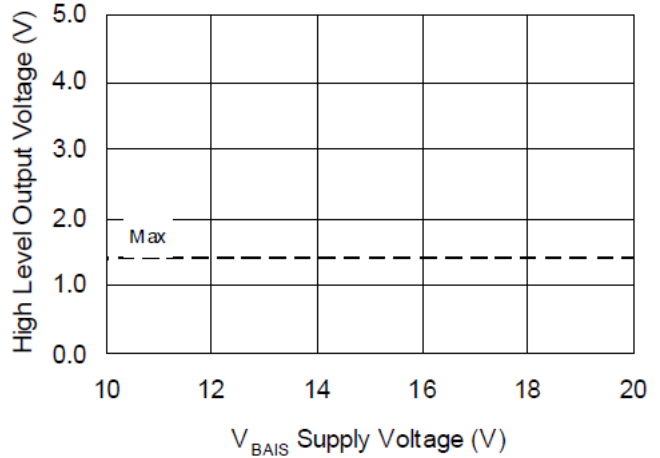


Figure 10B. High Level Output Voltage vs. Supply Voltage (Io = 0mA)

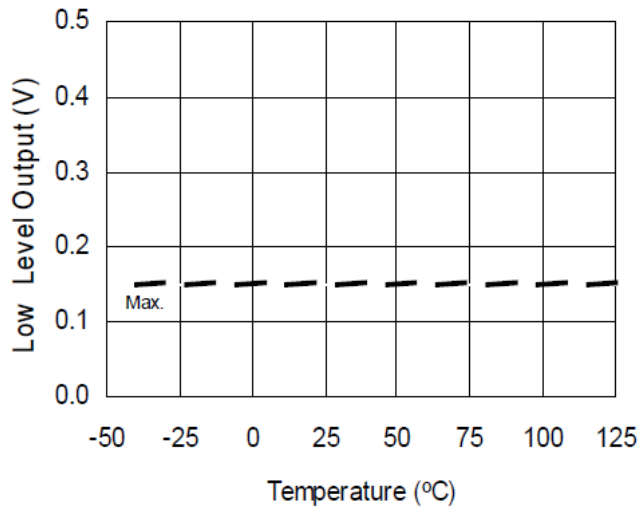


Figure 11A. Low Level Output vs. Temperature

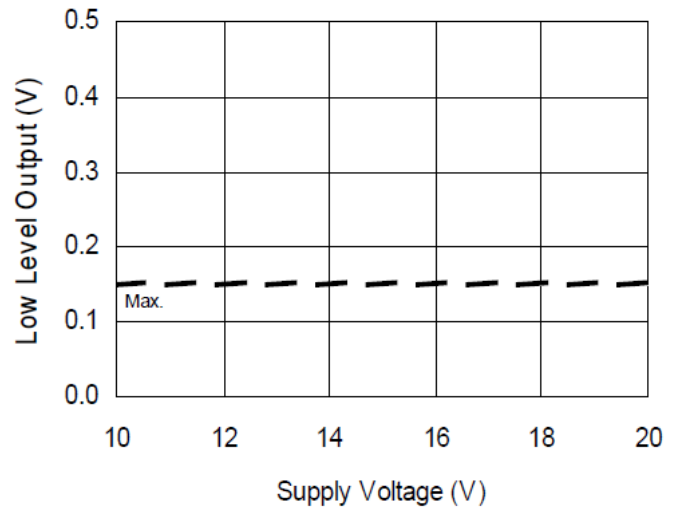


Figure 11B. Low Level Output vs. Supply Voltage

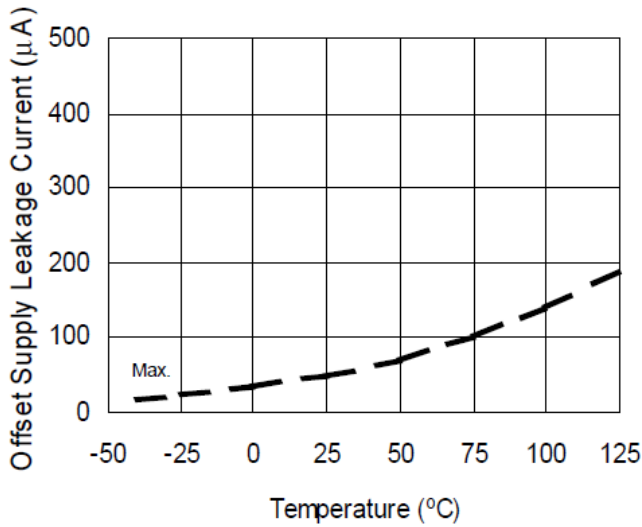


Figure 12A. Offset Supply Leakage Current

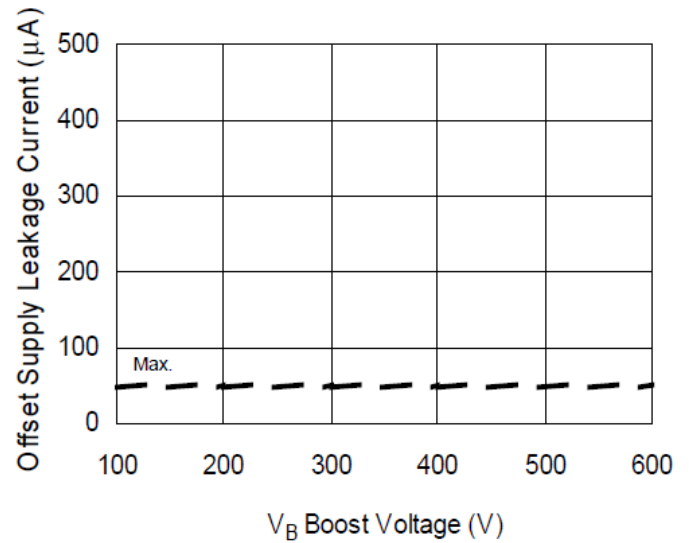


Figure 12B. Offset Supply Leakage Current vs. V_B Boost Voltage

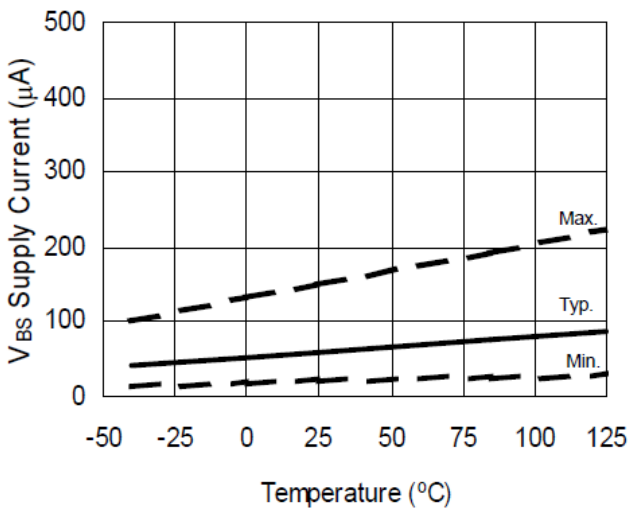


Figure 13A. V_{BS} Supply Current vs. Temperature

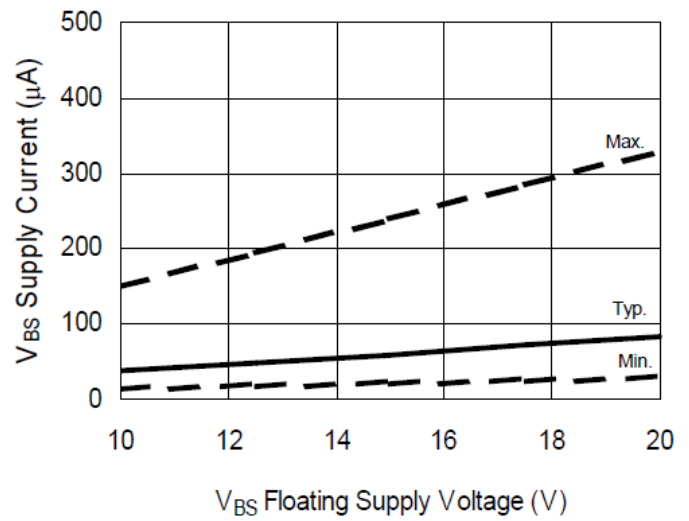


Figure 13B. V_{BS} Supply Current vs. V_{BS} Floating Supply Voltage

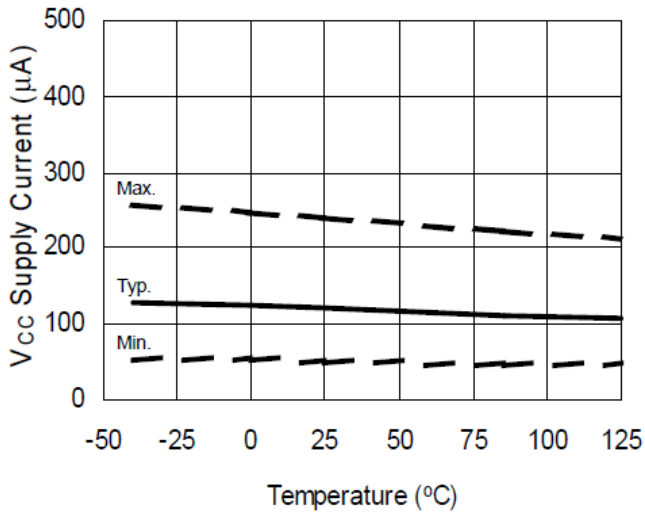


Figure 14A. V_{CC} Supply Current vs. Temperature

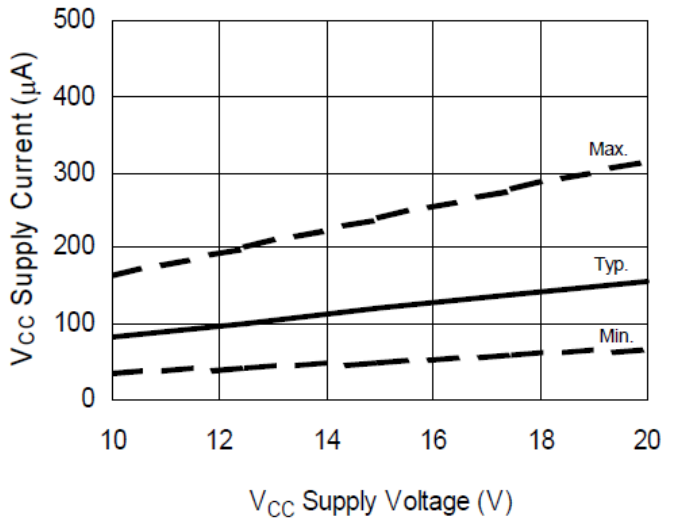


Figure 14B. V_{CC} Supply Current vs. Supply Voltage

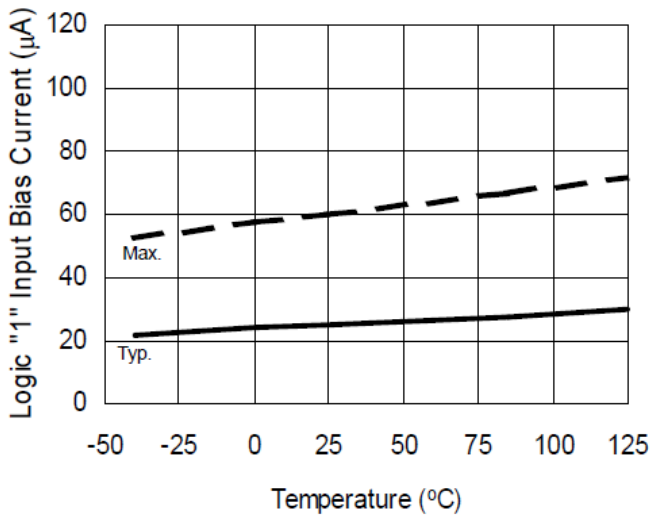


Figure 15A. Logic "1" Input Bias Current vs. Temperature

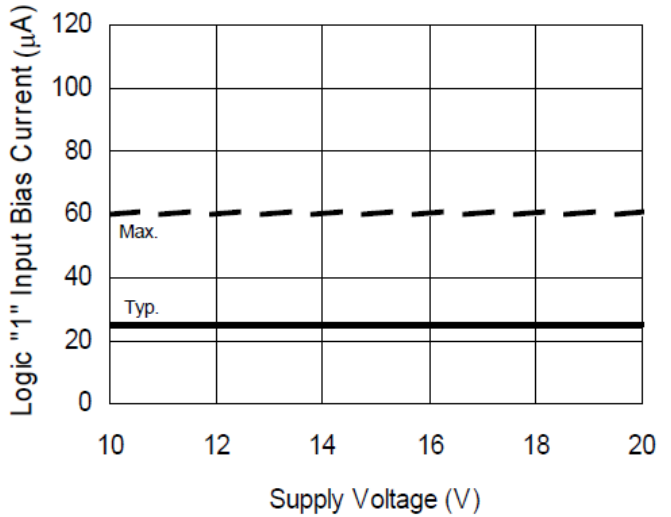


Figure 15B. Logic "1" Input Bias Current vs. Supply Voltage

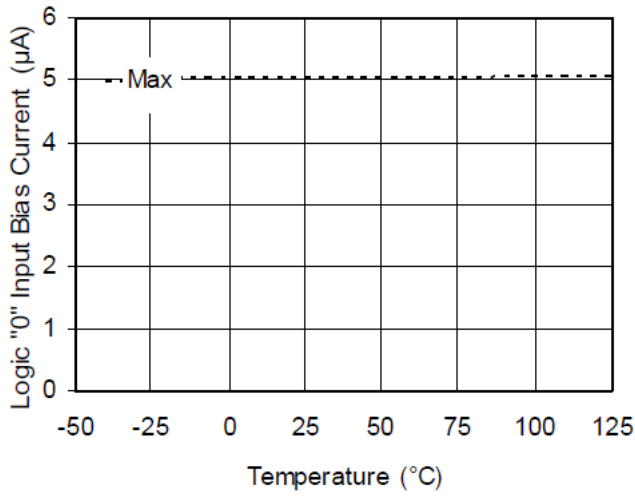


Figure 16A. Logic "0" Input Bias Current vs. Temperature

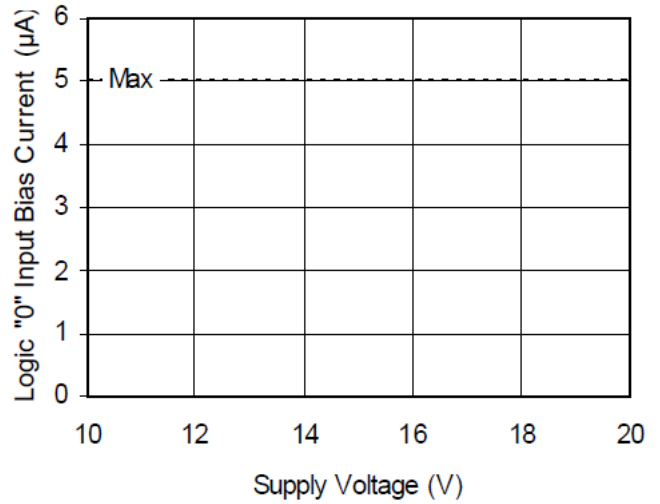


Figure 16B. Logic "0" Input Bias Current vs. Voltage

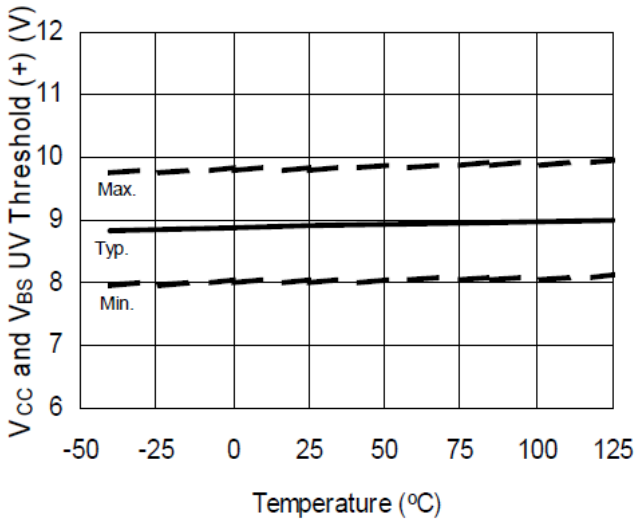


Figure 17. V_{CC} and V_{BS} Undervoltage Threshold (+) vs. Temperature

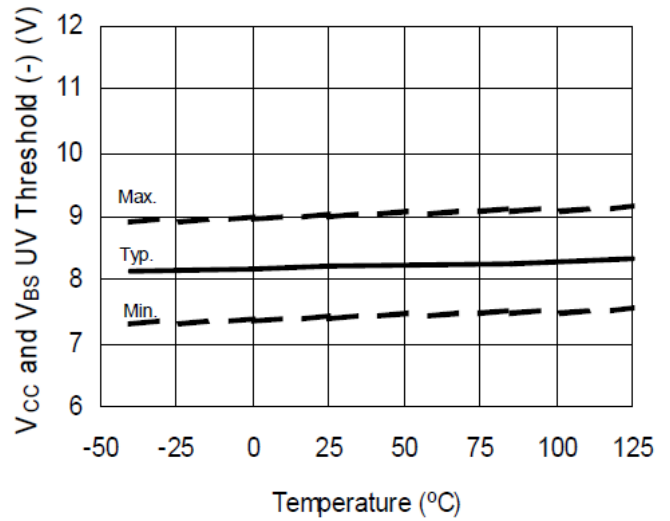


Figure 18. V_{CC} and V_{BS} Undervoltage Threshold (-) vs. Temperature

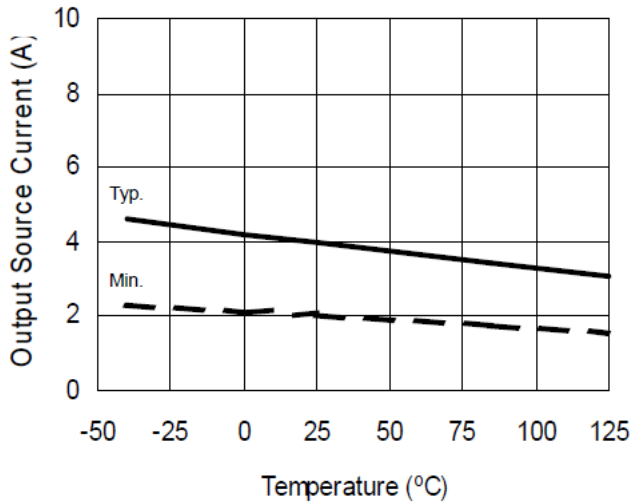


Figure 19A. Output Source Current vs. Temperature

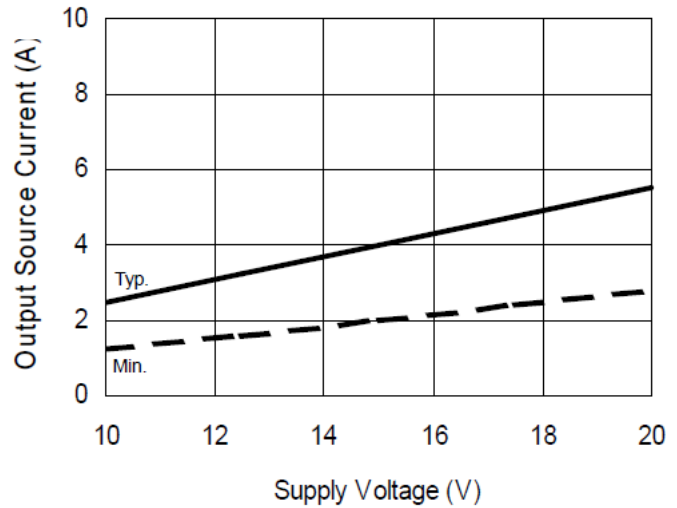


Figure 19B. Output Source Current vs. Supply Voltage

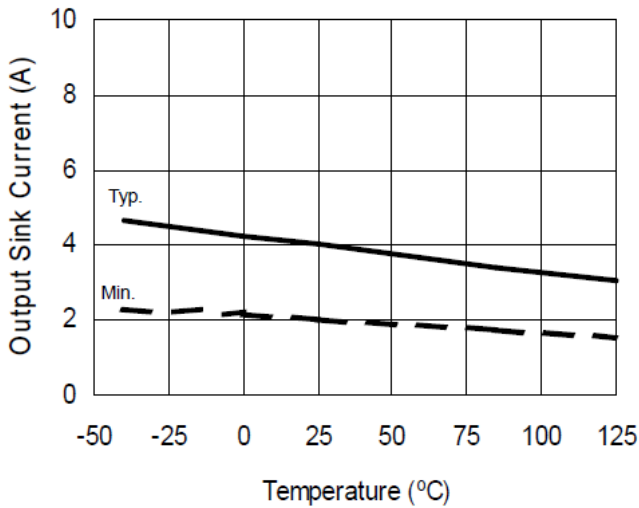


Figure 20A. Output Sink Current vs. Temperature

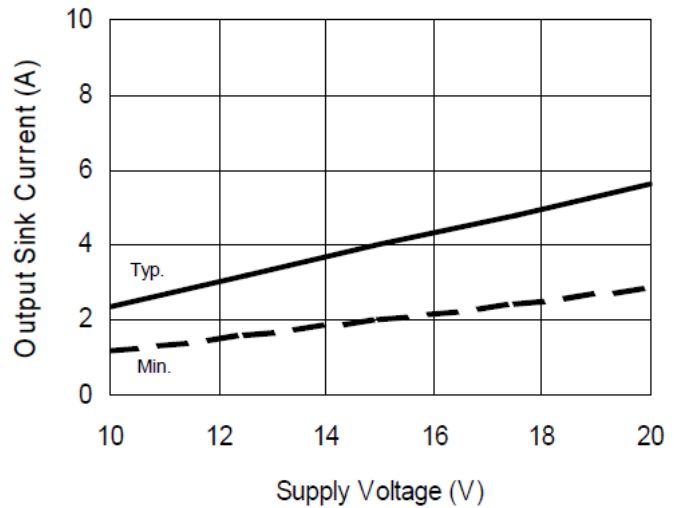


Figure 10B. Output Sink Current vs. Supply Voltage

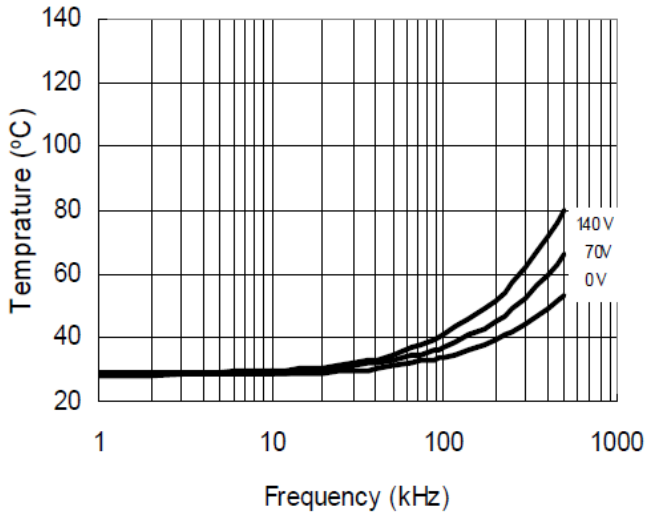


Figure 21. IRS2186 vs. Frequency (IRFBC20)
 $R_{gate} = 33\Omega, V_{CC} = 15V$

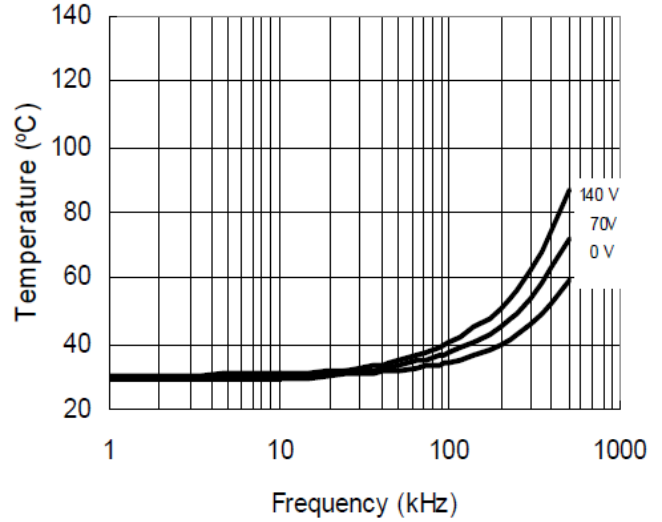


Figure 22. IRS2186 vs. Frequency (IRFBC30)
 $R_{gate} = 22\Omega, V_{CC} = 15V$

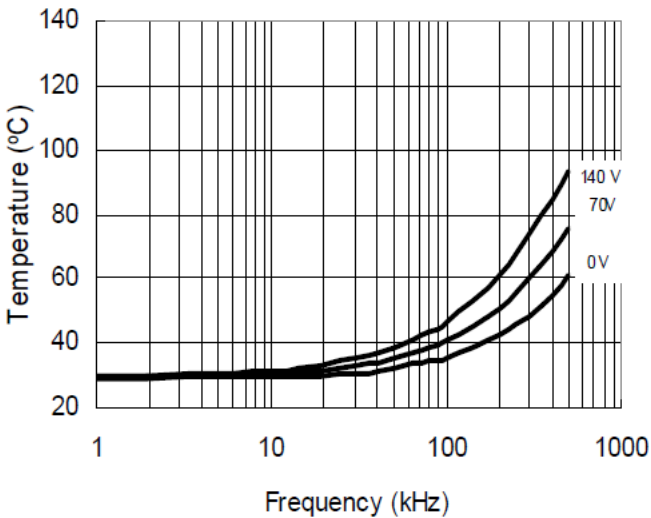


Figure 23. IRS2186 vs. Frequency (IRFBC40)
 $R_{gate} = 15\Omega, V_{CC} = 15V$

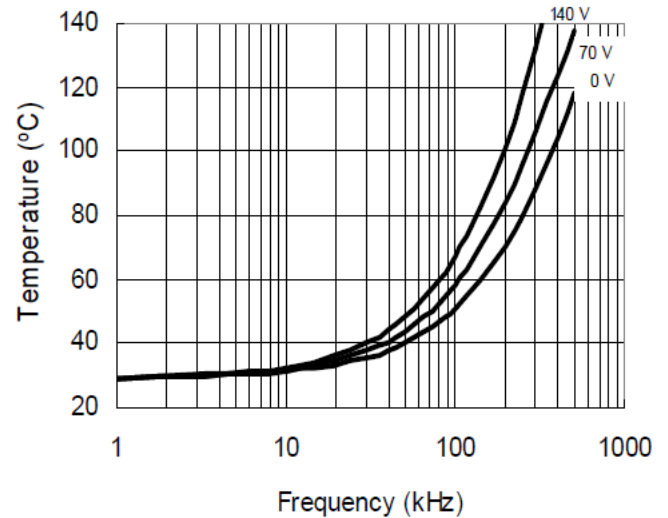


Figure 24. IRS2186 vs. Frequency (IRFPE50)
 $R_{gate} = 10\Omega, V_{CC} = 15V$

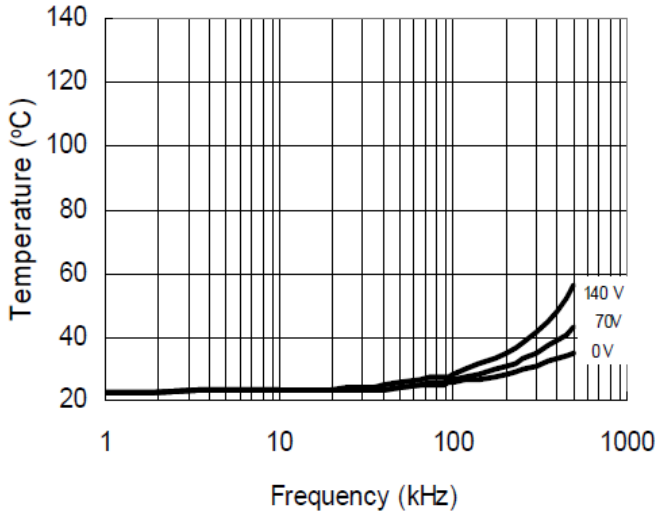


Figure 25. IRS21864 vs. Frequency (IRFBC20)
 $R_{gate} = 33\Omega, V_{CC} = 15V$

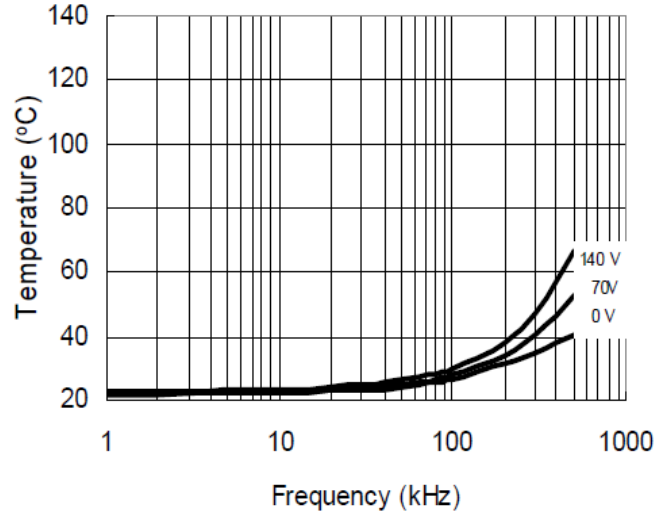


Figure 26. IRS21864 vs. Frequency (IRFBC30)
 $R_{gate} = 22\Omega, V_{CC} = 15V$

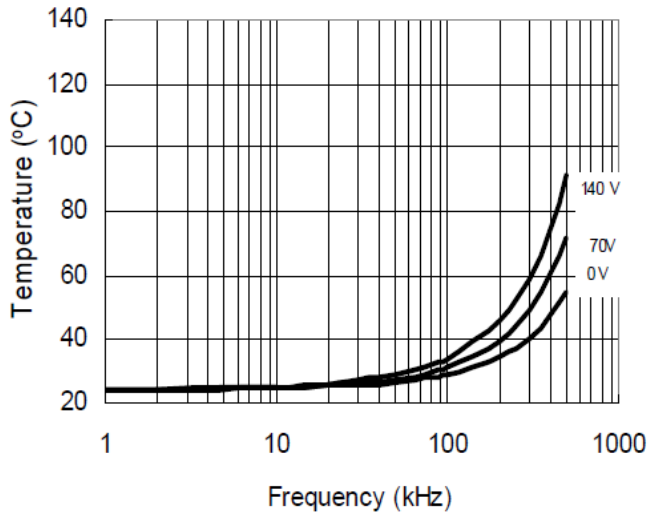


Figure 27. IRS21864 vs. Frequency (IRFBC40)
 $R_{gate} = 15\Omega, V_{CC} = 15V$

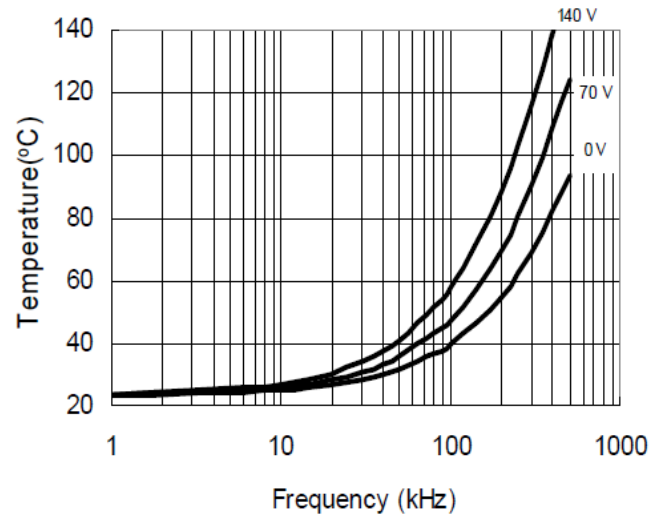


Figure 28. IRS21864 vs. Frequency (IRFPE50)
 $R_{gate} = 10\Omega, V_{CC} = 15V$

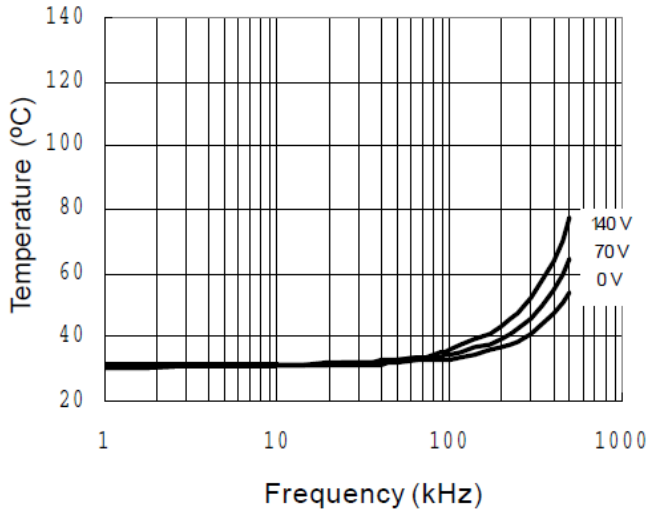


Figure 29. IRS2186S vs. Frequency (IRFBC20)
 $R_{gate} = 33\Omega, V_{CC} = 15V$

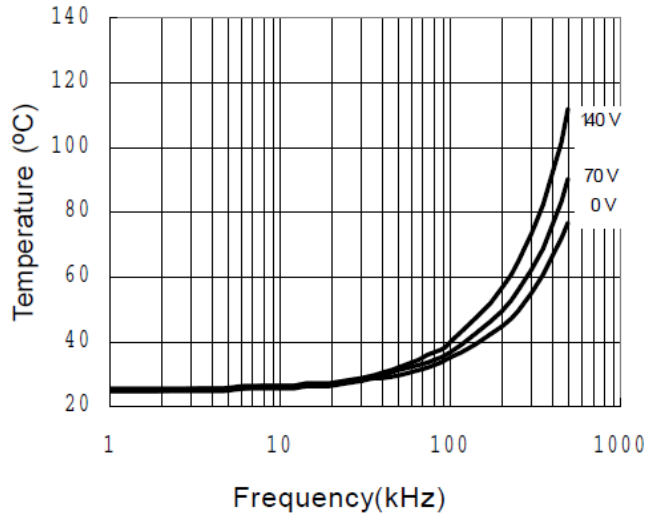


Figure 30. IRS2186S vs. Frequency (IRFBC30)
 $R_{gate} = 22\Omega, V_{CC} = 15V$

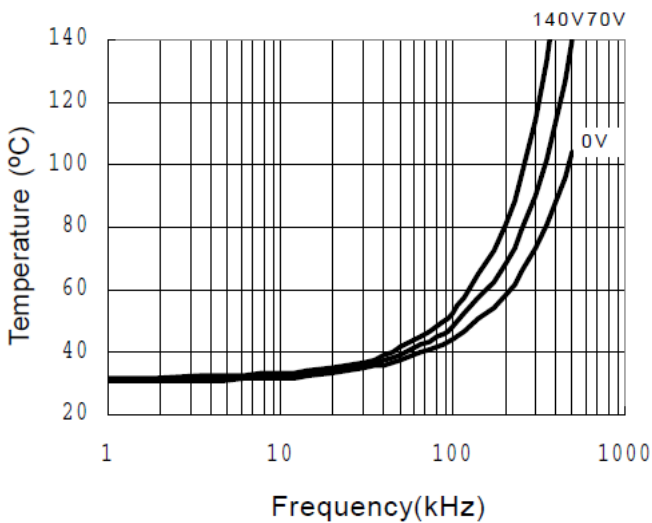


Figure 31. IRS2186S vs. Frequency (IRFBC40)
 $R_{gate} = 15\Omega, V_{CC} = 15V$

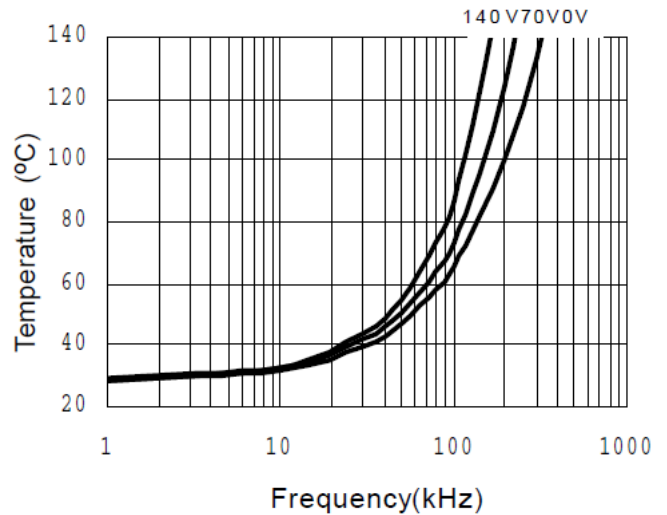


Figure 32. IRS2186S vs. Frequency (IRFPE50)
 $R_{gate} = 10\Omega, V_{CC} = 15V$

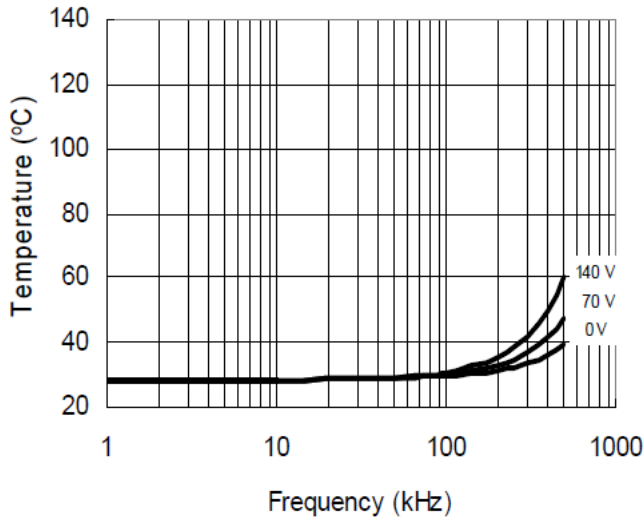


Figure 33. IRS21864S vs. Frequency (IRFBC20)
 $R_{gate} = 33\Omega, V_{CC} = 15V$

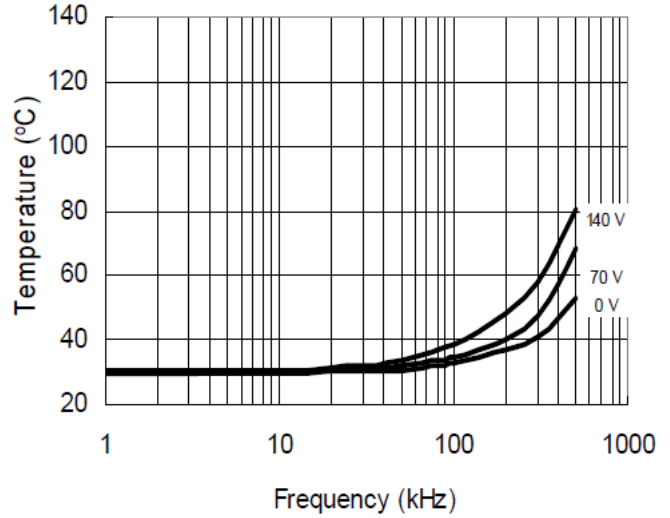


Figure 34. IRS21864S vs. Frequency (IRFBC30)
 $R_{gate} = 22\Omega, V_{CC} = 15V$

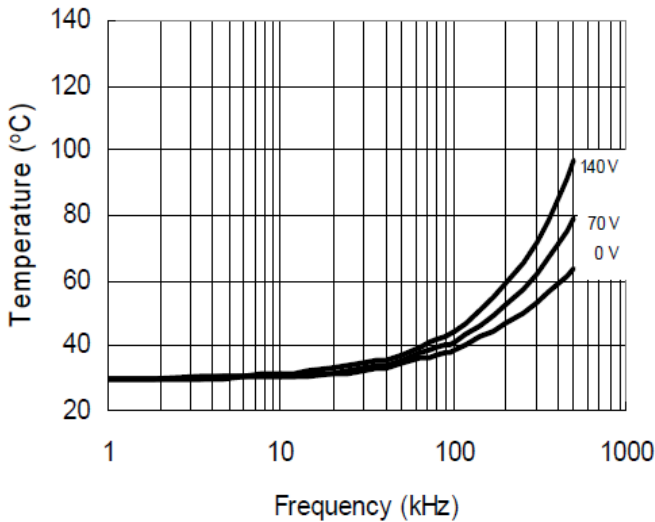


Figure 35. IRS21864S vs. Frequency (IRFBC40)
 $R_{gate} = 15\Omega, V_{CC} = 15V$

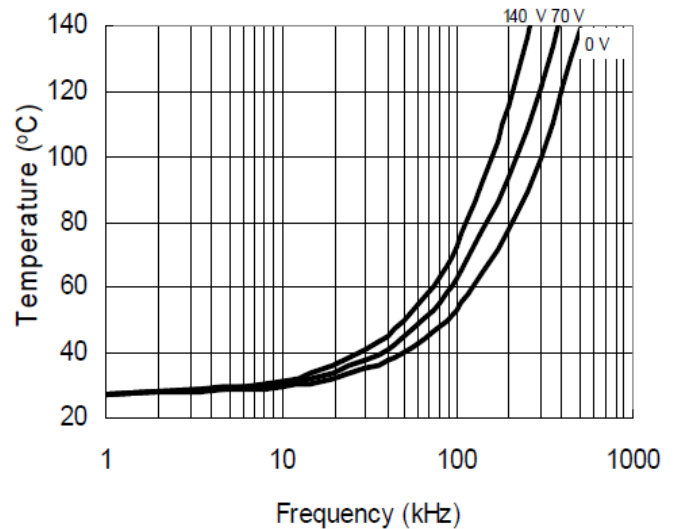
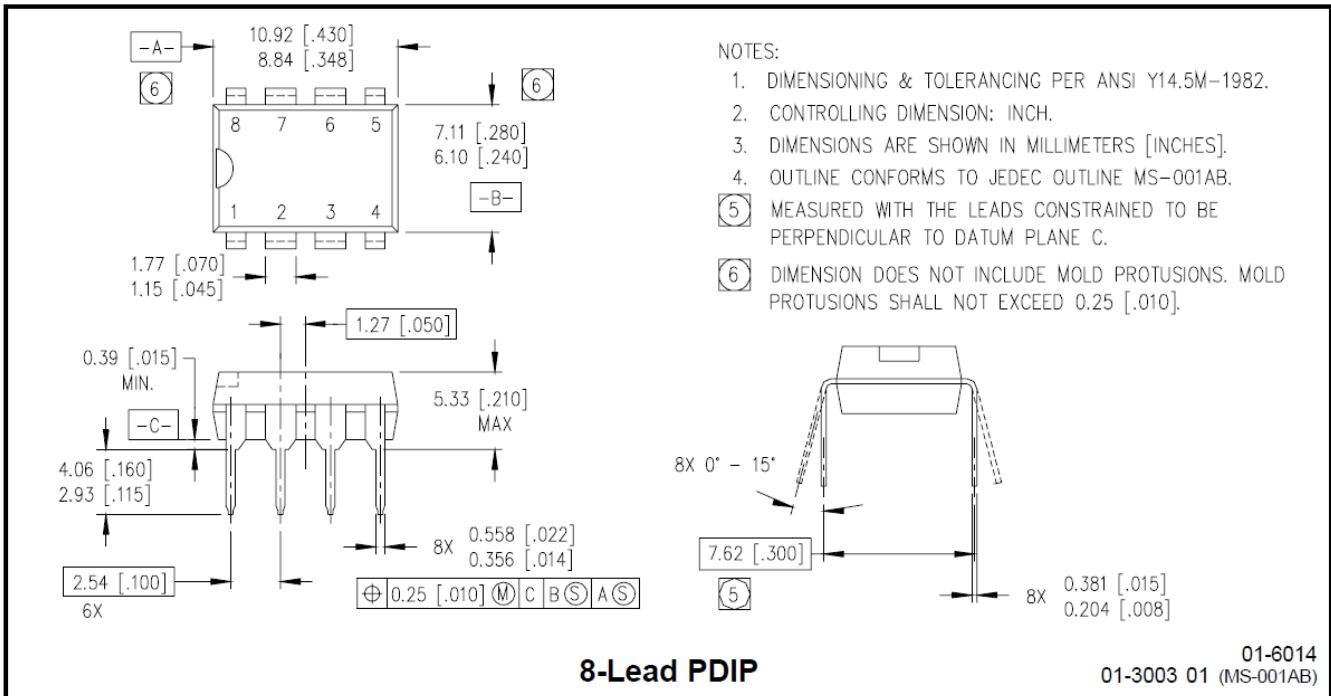
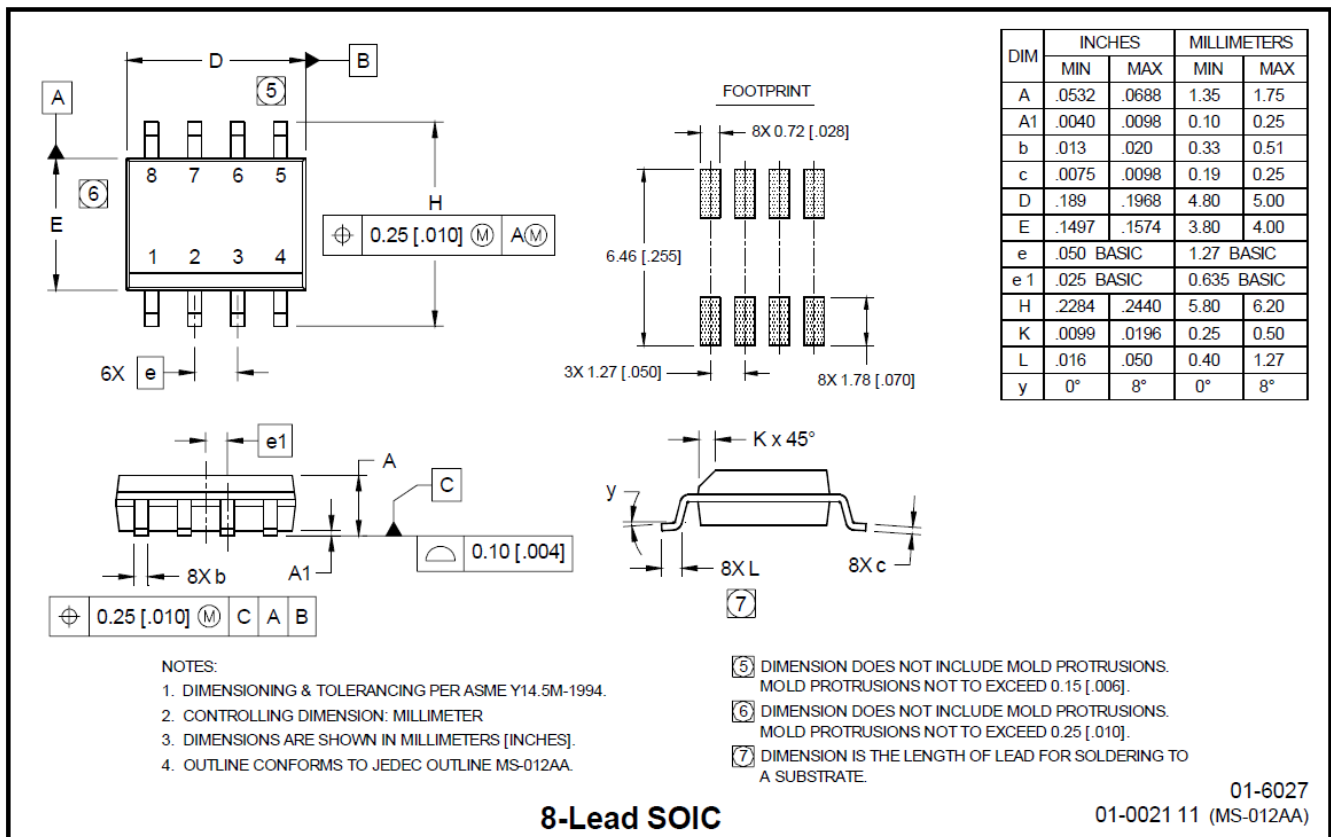
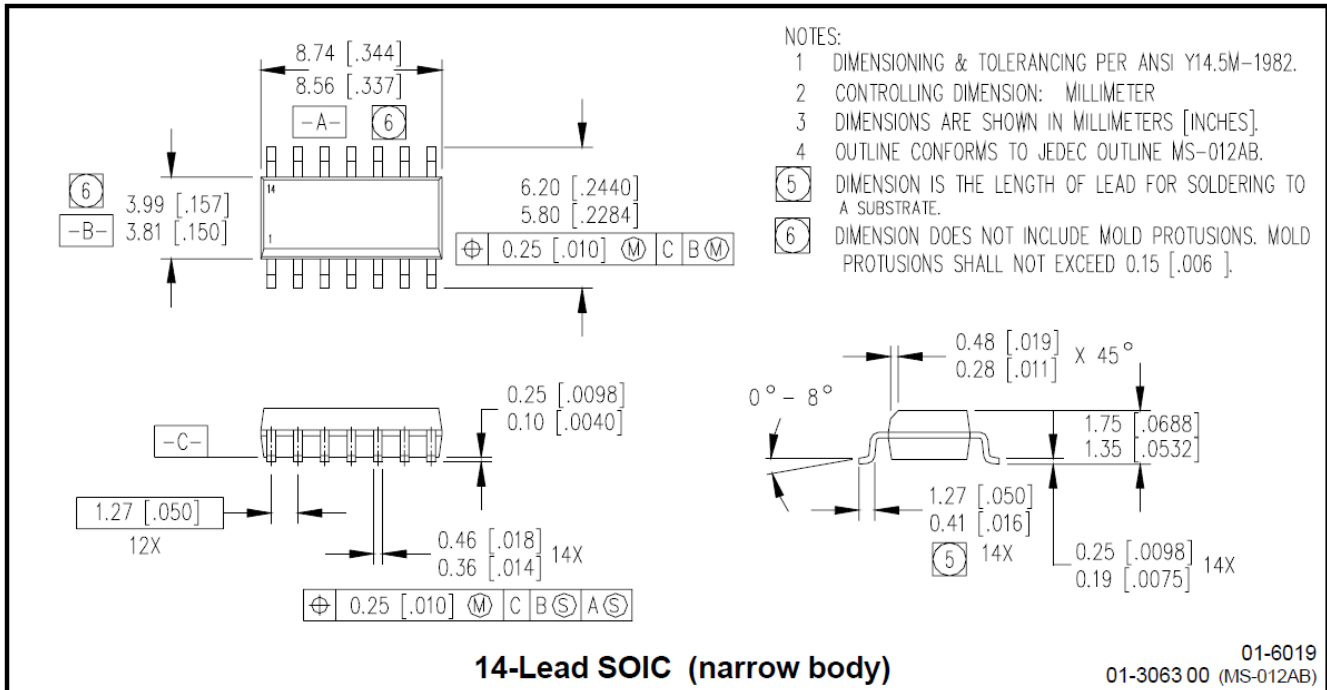
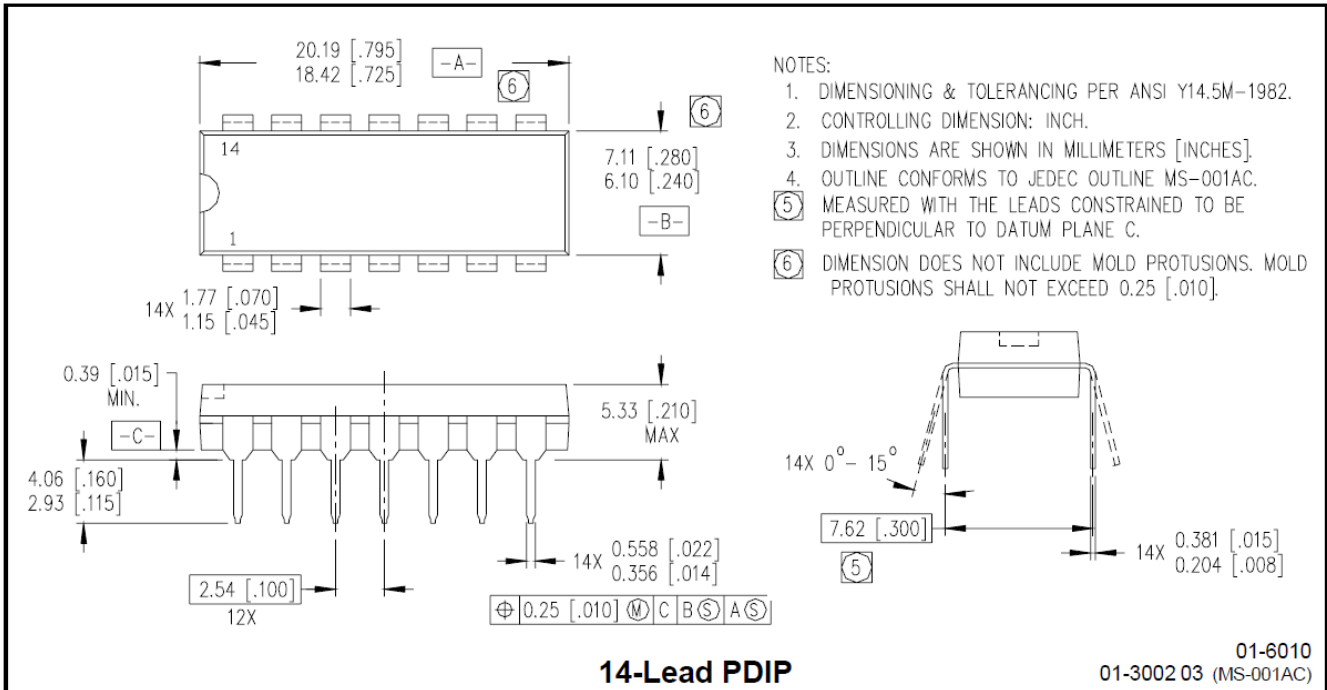
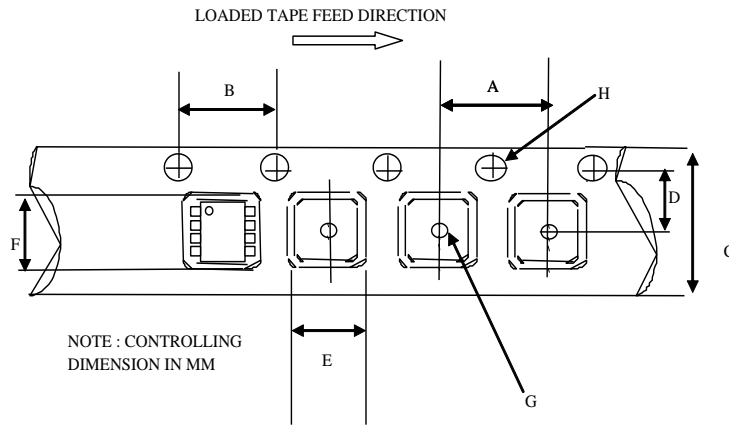


Figure 36. IRS21864S vs. Frequency (IRFPE50)
 $R_{gate} = 10\Omega, V_{CC} = 15V$

Package Details: PDIP8, SO8N

8-Lead PDIP

8-Lead SOIC

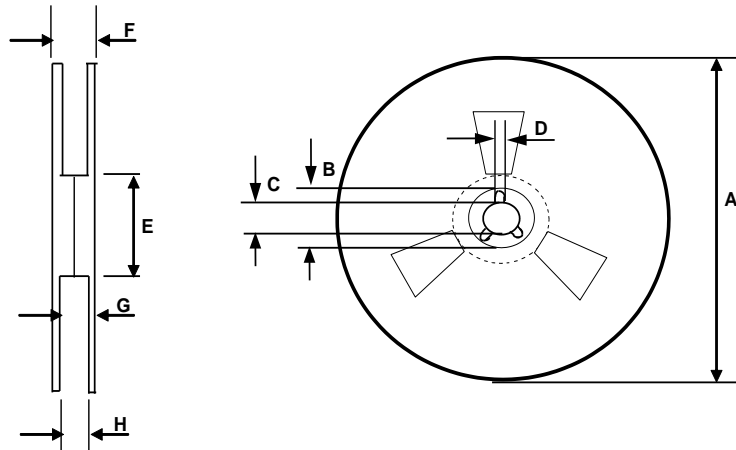
Package Details: PDIP14, SO14N


Tape and Reel Details: SO8N



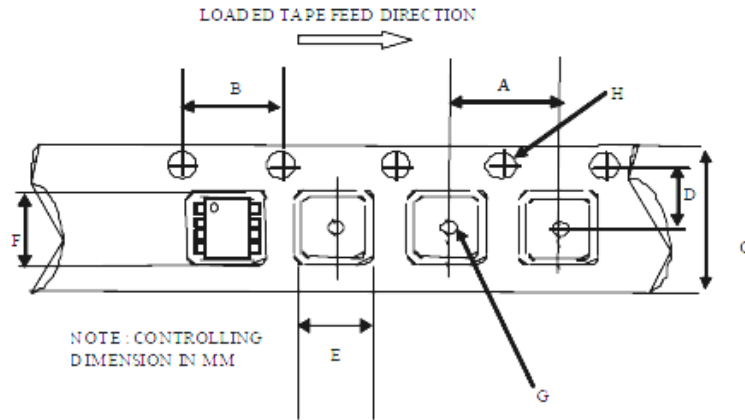
CARRIER TAPE DIMENSION FOR 8SOICN

| Code | Metric | | Imperial | |
|------|--------|-------|----------|-------|
| | Min | Max | Min | Max |
| A | 7.90 | 8.10 | 0.311 | 0.318 |
| B | 3.90 | 4.10 | 0.153 | 0.161 |
| C | 11.70 | 12.30 | 0.46 | 0.484 |
| D | 5.45 | 5.55 | 0.214 | 0.218 |
| E | 6.30 | 6.50 | 0.248 | 0.255 |
| F | 5.10 | 5.30 | 0.200 | 0.208 |
| G | 1.50 | n/a | 0.059 | n/a |
| H | 1.50 | 1.60 | 0.059 | 0.062 |

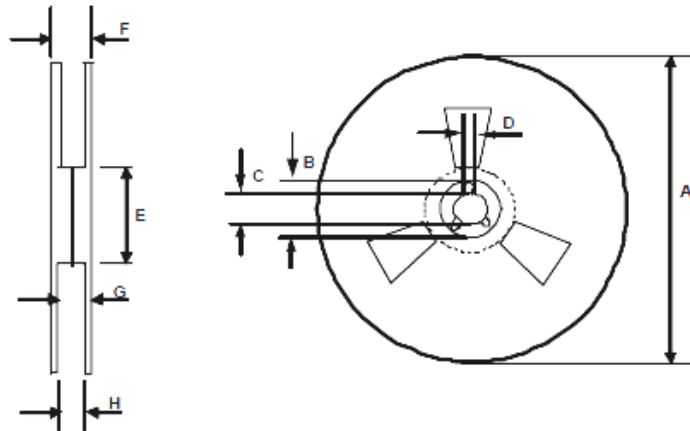


REEL DIMENSIONS FOR 8SOICN

| Code | Metric | | Imperial | |
|------|--------|--------|----------|--------|
| | Min | Max | Min | Max |
| A | 329.60 | 330.25 | 12.976 | 13.001 |
| B | 20.95 | 21.45 | 0.824 | 0.844 |
| C | 12.80 | 13.20 | 0.503 | 0.519 |
| D | 1.95 | 2.45 | 0.767 | 0.096 |
| E | 98.00 | 102.00 | 3.858 | 4.015 |
| F | n/a | 18.40 | n/a | 0.724 |
| G | 14.50 | 17.10 | 0.570 | 0.673 |
| H | 12.40 | 14.40 | 0.488 | 0.566 |

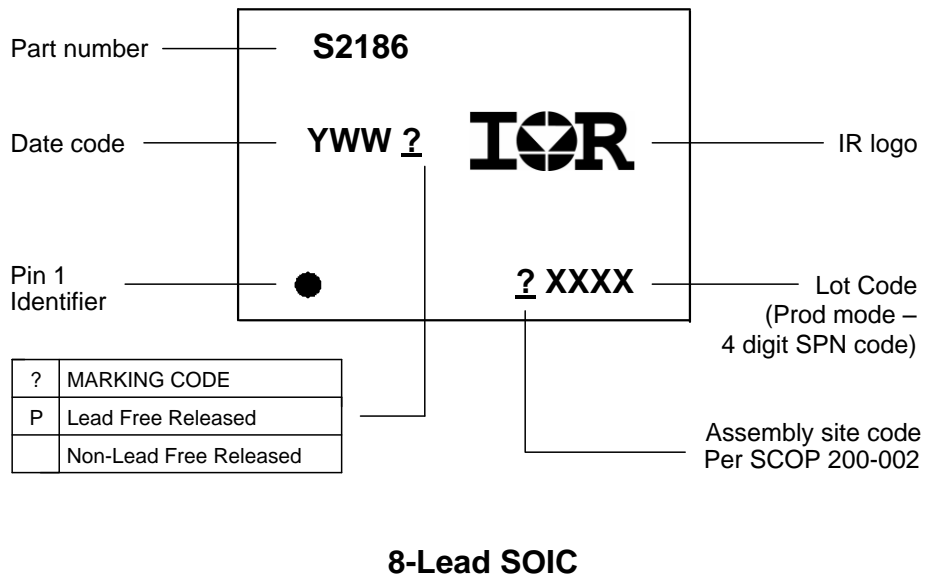
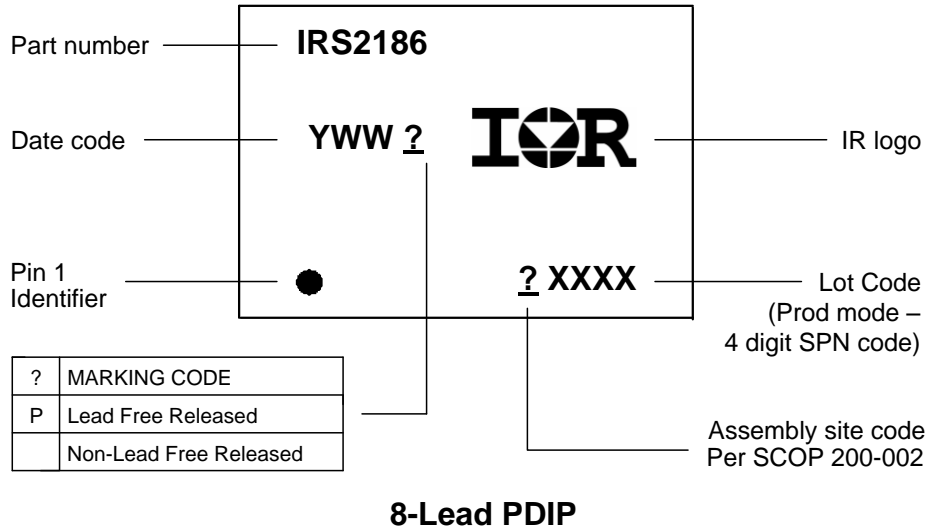
Tape and Reel Details: SO14N

CARRIER TAPE DIMENSION FOR 14SO1CN

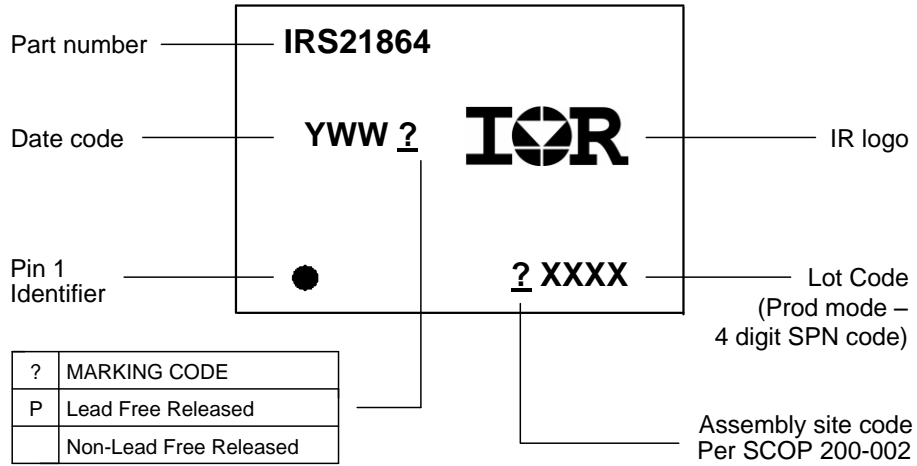
| Code | Metric | | Imperial | |
|------|--------|-------|----------|-------|
| | Min | Max | Min | Max |
| A | 7.90 | 8.10 | 0.311 | 0.318 |
| B 3 | .90 | 4.10 | 0.153 | 0.161 |
| C | 15.70 | 16.30 | 0.618 | 0.641 |
| D | 7.40 | 7.60 | 0.291 | 0.299 |
| E | 6.40 | 6.60 | 0.252 | 0.260 |
| F | 9.40 | 9.60 | 0.370 | 0.378 |
| G | 1.50 | n/a | 0.059 | n/a |
| H | 1.50 | 1.60 | 0.059 | 0.062 |


REEL DIMENSIONS FOR 14SO1CN

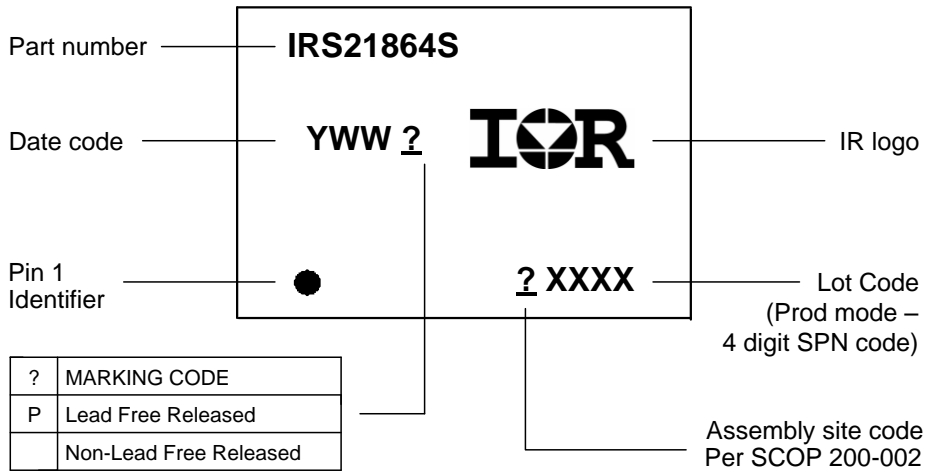
| Code | Metric | | Imperial | |
|------|--------|--------|----------|--------|
| | Min | Max | Min | Max |
| A | 329.60 | 330.25 | 12.976 | 13.001 |
| B | 20.95 | 21.45 | 0.824 | 0.844 |
| C | 12.80 | 13.20 | 0.503 | 0.519 |
| D | 1.95 | 2.45 | 0.767 | 0.096 |
| E | 98.00 | 102.00 | 3.858 | 4.015 |
| F | n/a | 22.40 | n/a | 0.881 |
| G | 18.50 | 21.10 | 0.728 | 0.830 |
| H | 16.40 | 18.40 | 0.645 | 0.724 |

Part Marking Information





14-Lead PDIP



14-Lead SOIC

Qualification Information[†]

| | | |
|-----------------------------------|---|---|
| Qualification Level | Industrial ^{††} (per JEDEC JESD 47) | |
| | Comments: This family of ICs has passed JEDEC's Industrial qualification. IR's Consumer qualification level is granted by extension of the higher Industrial level. | |
| Moisture Sensitivity Level | SOIC8N | MSL2 ^{†††} (per IPC/JEDEC J-STD 020) |
| | PDIP8 | Not applicable (non-surface mount package style) |
| | SOIC14N | MSL2 ^{†††} (per IPC/JEDEC J-STD 020) |
| | PDIP14 | Not applicable (non-surface mount package style) |
| RoHS Compliant | Yes | |

† Qualification standards can be found at International Rectifier's web site <http://www.irf.com/>

†† Higher qualification ratings may be available should the user have such requirements. Please contact your International Rectifier sales representative for further information.

††† Higher MSL ratings may be available for the specific package types listed here. Please contact your International Rectifier sales representative for further information.

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For technical support, please contact IR's Technical Assistance Center
<http://www.irf.com/technical-info/>

WORLD HEADQUARTERS:
 233 Kansas St., El Segundo, California 90245
 Tel: (310) 252-7105



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



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